

V_{DSS} , 100V R_{DS(ON)} , 27mΩ (max.) @ V_{GS}=10V R_{DS(ON)} , 28.5mΩ (max.) @ V_{GS}=4.5V I_D , 38A	TO-220AB	

Description	Features
The SG100N03P uses advanced Trench technology and designs to provide excellent R _{DS(ON)} with low gate charge. This device is suitable for use in PWM, load switching and general purpose applications.	<ul style="list-style-type: none"> • Low On-Resistance • Low Input Capacitance • Low Miller Charge • Low Input / Output Leakage • Pb-free lead plating; RoHS compliant
	Applications
	<ul style="list-style-type: none"> • Motor / Body Load Control • Automotive Systems • Load Switch • DC-DC converters and Off-line UPS

Ordering Information

Ordering Code	RoHS Status	Package	Package Code	Packing	Quantity
SG100N03P	Halogen-Free	TO-220AB	P	Tube	50

Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	T _A =25°C	38
		T _A =100°C	24
Drain Current-Pulsed ^{Note 1}	I _{DM}	39	A
Avalanche Current, L=0.1mH	I _{AS}	24	A
Avalanche Energy, L=0.1mH	E _{AS}	29	mJ
Maximum Power Dissipation	P _D	T _A =25°C	83.9
		T _A =100°C	33.6
Operating Junction Temperature Range	T _J	150	°C

Thermal Resistance Ratings

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Thermal resistance, Junction-to-Ambient ^{Note 2}	R _{θJA}	Steady State	-	40.7		°C/W
Thermal resistance, Junction-to-Case ^{Note 2}	R _{θJC}	Steady State	-	1.49		°C/W

Electrical Characteristics (T_J=25°C unless otherwise noted)

OFF CHARACTERISTICS						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _{DS} =250μA	100	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =80V, V _{GS} =0V	-	-	1	μA
Gate-Body Leakage	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA

ON CHARACTERISTICS						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Gate Threshold Voltage	V _{GS(TH)}	V _{DS} =V _{GS} , I _{DS} =250μA	1.2	1.8	2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _{DS} =20A	-	-	27	mΩ
		V _{GS} =4.5V, I _{DS} =10A	-	-	28.5	

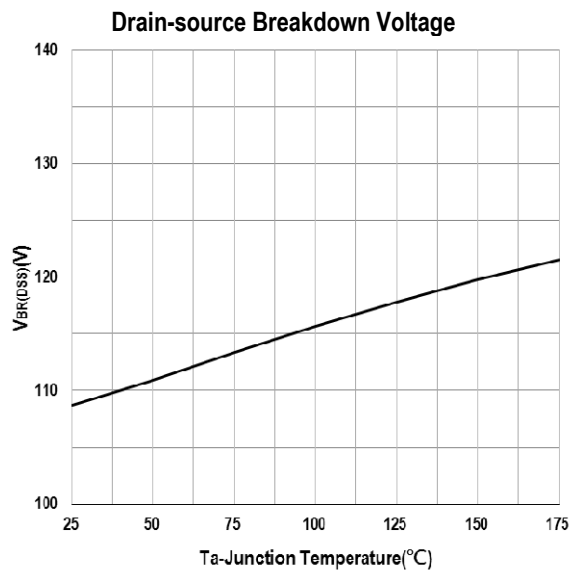
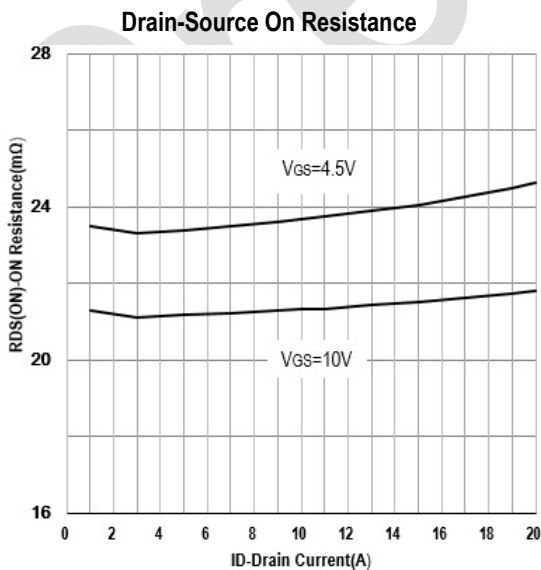
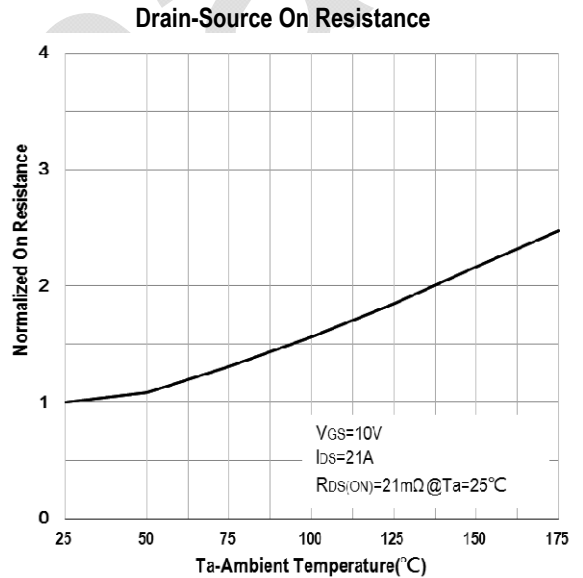
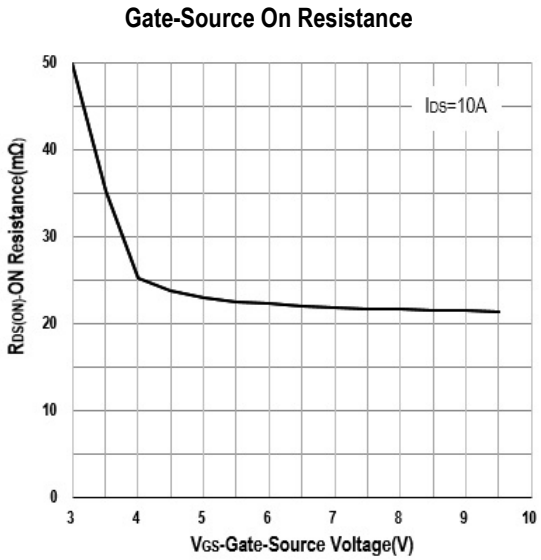
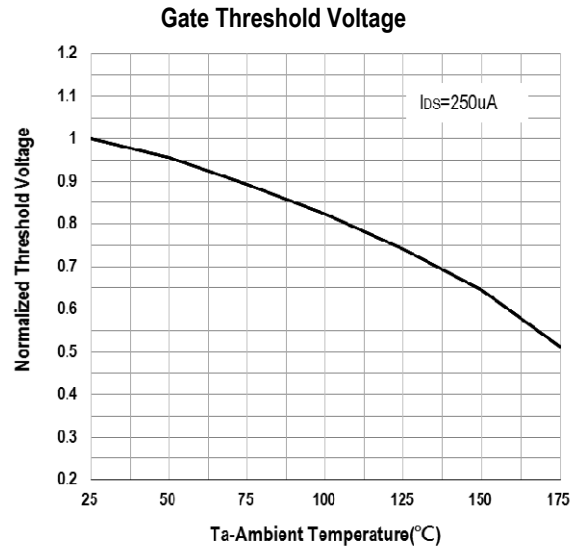
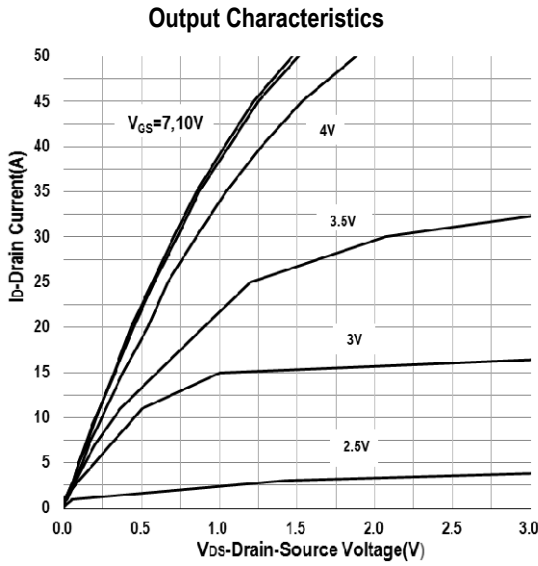
DYNAMIC CHARACTERISTICS						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Input Capacitance	C _{iss}	V _{DS} =40V, V _{GS} =0V, f=1MHz	-	1858	-	pF
Output Capacitance	C _{oss}		-	113	-	
Reverse Transfer Capacitance	C _{rss}		-	47	-	

SWITCHING CHARACTERISTICS						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Turn-On Delay Time	T _{d(on)}	V _{DS} =50V, V _{GS} =10V, R _G =3Ω, I _D =10A	-	9	-	ns
Rise Time	t _r		-	7.8	-	
Turn-Off Delay Time	T _{d(off)}		-	28.9	-	
Fall Time	t _f		-	16	-	
Total Gate Charge at 10V	Q _g	V _{GS} =10V, V _{DS} =50V, I _D =10A	-	36.6	-	nC
Gate to Source Gate Charge	Q _{gs}		-	8.1	-	
Gate to Drain "Miller" Charge	Q _{gd}		-	7.1	-	

DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =10A	-	-	1.3	V
Body Diode Reverse Recovery Time	t _{rr}	I _F =10A, di/dt=500A/μs	-	24.4	-	ns
Body Diode Reverse Recovery Charge	Q _{rr}		-	107.5	-	nC
Reverse Recovery Current	I _{RRM}	V _{DS} =50V, I _F =10A, di/dt=500A/μs	-	8.8	-	A

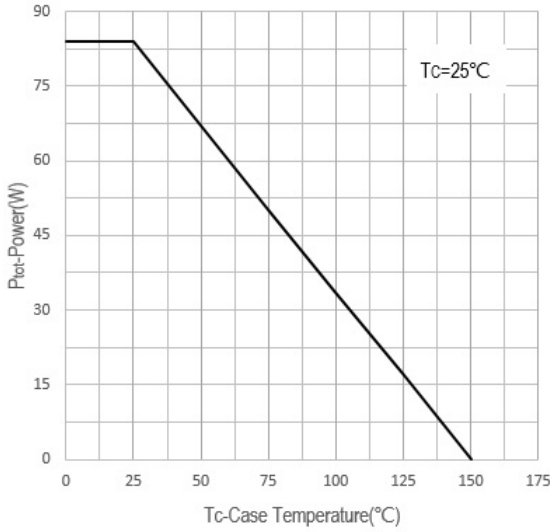
- Notes:**
- Pulse Test: Pulse Width ≤ 10ms, Duty Cycle ≤ 1%.
 - R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{θJC} is guaranteed by design while R_{θJA} is determined by the user's board design. R_{θJA} shown below for single device operation on FR-4 in still air.

Typical Operating Characteristics

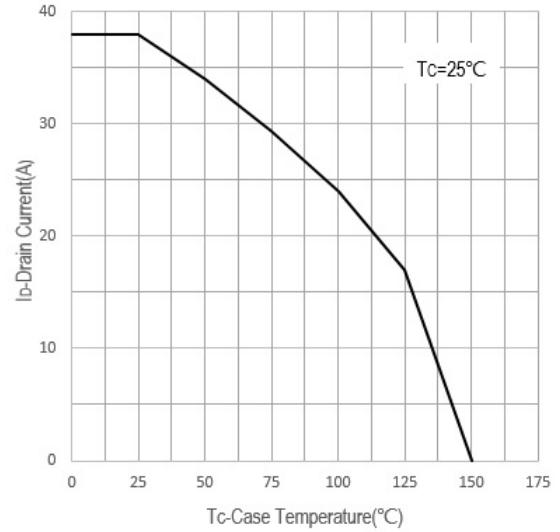


Typical Operating Characteristics (Cont.)

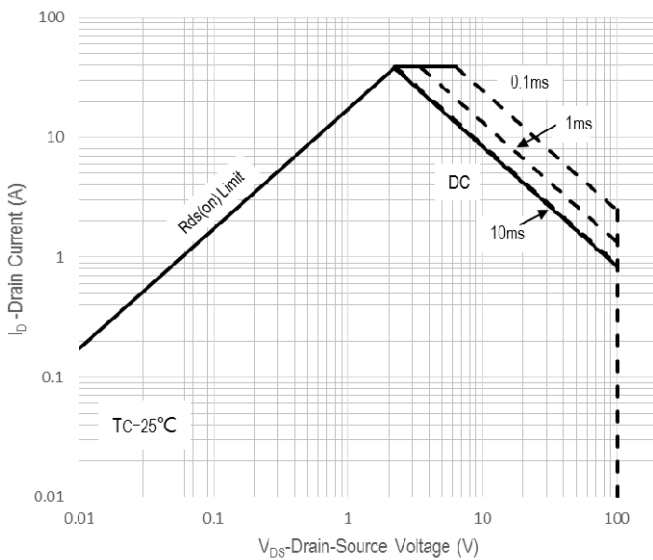
Power Dissipation



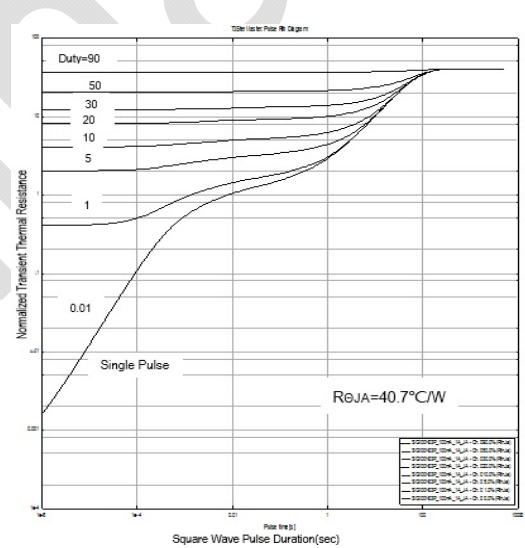
Drain Current



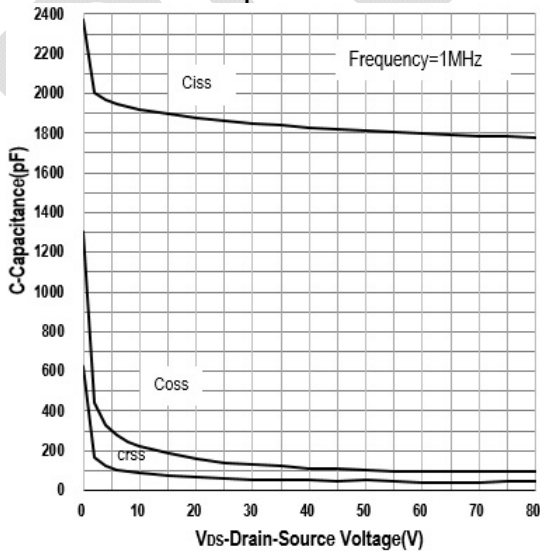
Safe Operation Area



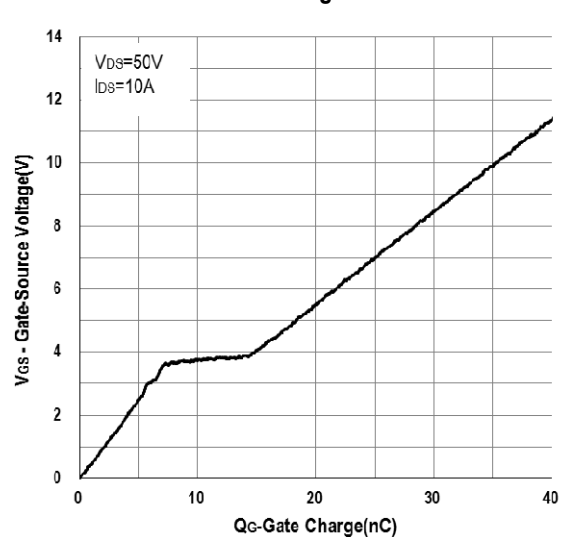
Thermal Transient Impedance



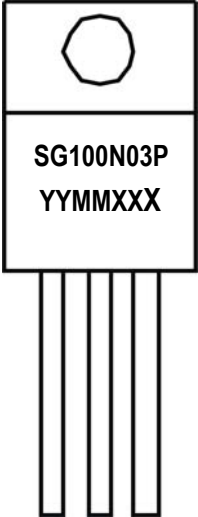
Capacitance



Gate Charge

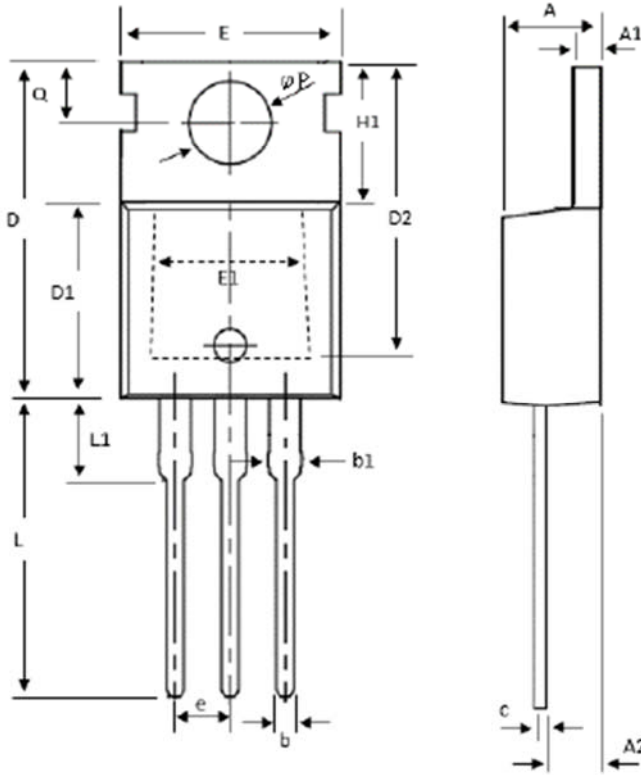


Marking Information

TO-220AB (P)	Marking Rule
<p>Laser Marking</p> 	<p><u>Line 1</u> : Device SG100N03P</p> <p><u>Line 2</u> : Date Code YYMMXXX</p> <p>YY : Year Code MM : Month XXX : Serial Number</p>

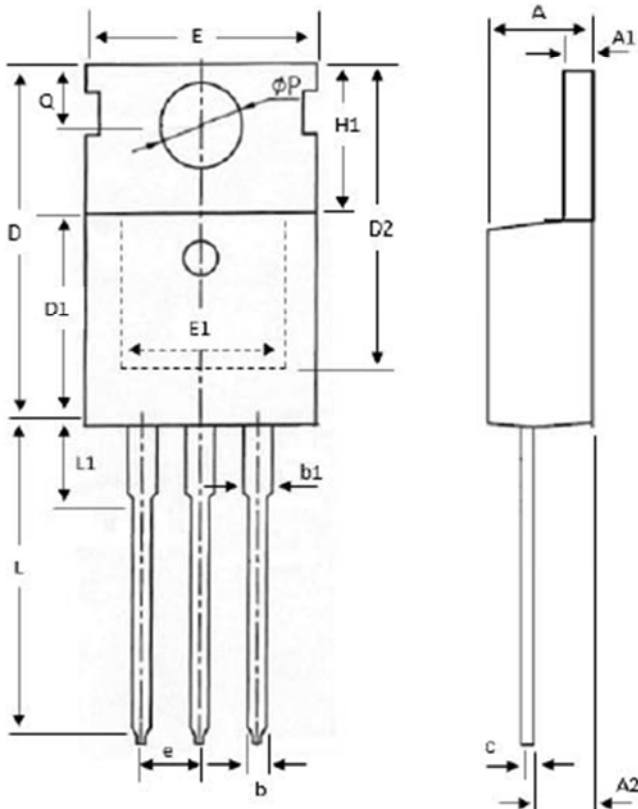
Package of Dimension

G-TYPE



Symbol	Min	Nor	Max
A	4.20	4.45	4.70
A1	1.15	1.28	1.40
A2	2.20	2.45	2.70
b	0.70	0.83	0.95
b1	1.15	1.45	1.75
c	0.40	0.50	0.60
D1	8.80	9.10	9.40
D2	11.75	-	-
E	9.70	10.03	10.36
E1	6.86	-	-
e	2.54 BSC		
H1	6.25	6.55	6.85
L	12.75	13.38	14.00
L1	-	-	4.00
P	3.40	3.70	4.00
Q	2.60	2.80	3.00

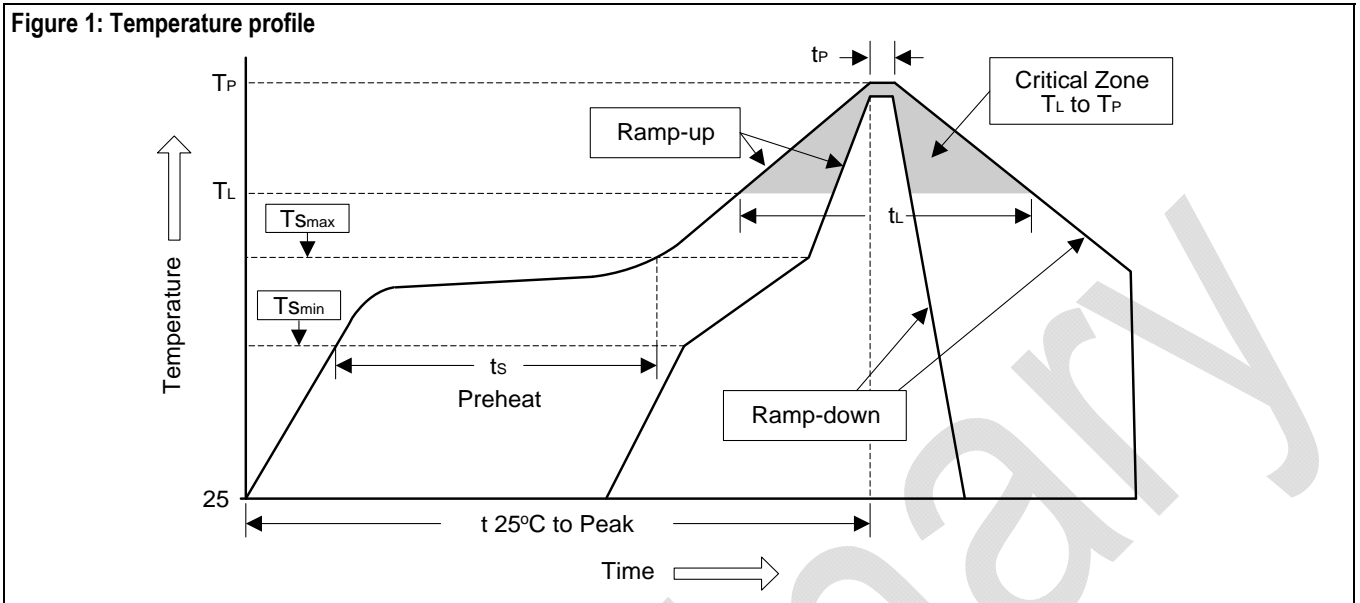
P-TYPE
H-TYPE



Soldering Methods for Silicongear's Products

1. Storage environment: Temperature=10°C to 35°C Humidity=65%±15%
2. Reflow soldering of surface-mount devices

Figure 1: Temperature profile



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	<3°C/sec	<3°C/sec
Preheat		
- Temperature Min (T_{Smin})	100°C	150°C
- Temperature Max (T_{Smax})	150°C	200°C
- Time (min to max) (t_s)	60 to 120 sec	60 to 180 sec
T_{Smax} to T_L		
- Ramp-up Rate	<3°C/sec	<3°C/sec
Time maintained above:		
- Temperature (T_L)	183°C	217°C
- Time (t_L)	60 to 150 sec	60 to 150 sec
Peak Temperature (T_P)	240°C +0/-5°C	260°C +0/-5°C
Time within 5°C of actual Peak Temperature (t_P)	10 to 30 sec	20 to 40 sec
Ramp-down Rate	<6°C/sec	<6°C/sec
Time 25°C to Peak Temperature	<6 minutes	<8 minutes

3. Flow (wave) soldering (solder dipping)

Products	Peak Temperature	Dipping Time
Pb devices.	245°C ±5°C	5sec ±1sec
Pb-Free devices.	260°C +0/-5°C	5sec ±1sec

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